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ON Semiconductor®

FDS86141

N-Channel Power Trench® MOSFET

100 V, 7 A, 23 mΩ

Features

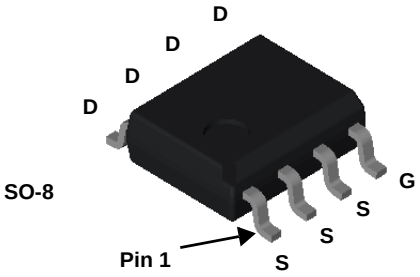
- Max $r_{DS(on)}$ = 23 mΩ at V_{GS} = 10 V, I_D = 7 A
- Max $r_{DS(on)}$ = 36 mΩ at V_{GS} = 6 V, I_D = 5.5 A
- High performance trench technology for extremely low $r_{DS(on)}$
- 100% UIL Tested
- RoHS Compliant

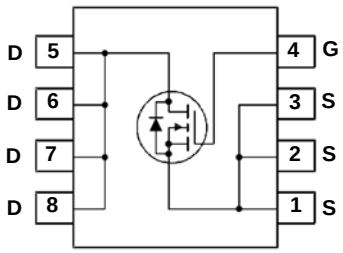
General Description

This N-Channel MOSFET is produced using ON Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintaiin superior switching performance.

Applications

- DC-DC Conversion





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
I_D	Drain Current -Continuous			7	A
	-Pulsed			30	
E_{AS}	Single Pulse Avalanche Energy		(Note 3)	121	mJ
P_D	Power Dissipation	T_A = 25 °C	(Note 1a)	2.5	W
	Power Dissipation	T_A = 25 °C	(Note 1b)	1.0	
T_J, T_{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS86141	FDS86141	SO-8	13 ”	12 mm	2500 units

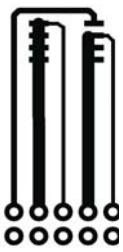
Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA, V_{GS} = 0 V	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		67		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 80 V, V_{GS} = 0 V			1	μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA
On Characteristics						
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA	2	3.1	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		-10		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 7 A		19	23	mΩ
		V_{GS} = 6 V, I_D = 5.5 A		27	37	
		V_{GS} = 10 V, I_D = 7 A, T_J = 125 °C		33	40	
g_{FS}	Forward Transconductance	V_{DS} = 10 V, I_D = 7 A		19		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 50 V, V_{GS} = 0 V, f = 1 MHz		703	934	pF
C_{oss}	Output Capacitance			186	247	pF
C_{rss}	Reverse Transfer Capacitance			8.6	13	pF
R_g	Gate Resistance			0.5		Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 50 V, I_D = 7 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		8.3	17	ns
t_r	Rise Time			3.2	10	ns
$t_{d(off)}$	Turn-Off Delay Time			14.3	26	ns
t_f	Fall Time			3.2	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 0 V to 10 V; V_{DD} = 50 V, I_D = 7 A		11.8	16.5	nC
	Total Gate Charge	V_{GS} = 0 V to 5 V; V_{DD} = 50 V, I_D = 7 A		6.7	9.4	nC
Q_{gs}	Total Gate Charge	V_{DD} = 50 V, I_D = 7 A		3.4		nC
Q_{gd}	Gate to Drain “Miller” Charge			3.1		nC
Drain-Source Diode Characteristics						
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 7 A (Note 2)		0.8	1.3	V
		V_{GS} = 0 V, I_S = 2 A (Note 2)		0.8	1.2	
t_{rr}	Reverse Recovery Time	I_F = 7 A, di/dt = 100 A/μs		43	69	ns
Q_{rr}	Reverse Recovery Charge			39	62	nC

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a) 50 °C/W when mounted on a 1 in^2 pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0 %.

3. Starting T_J = 25 °C; N-ch: L = 3 mH, I_{AS} = 9 A, V_{DD} = 100 V, V_{GS} = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

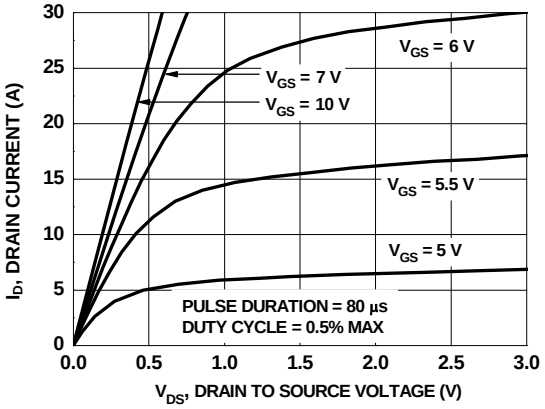


Figure 1. On-Region Characteristics

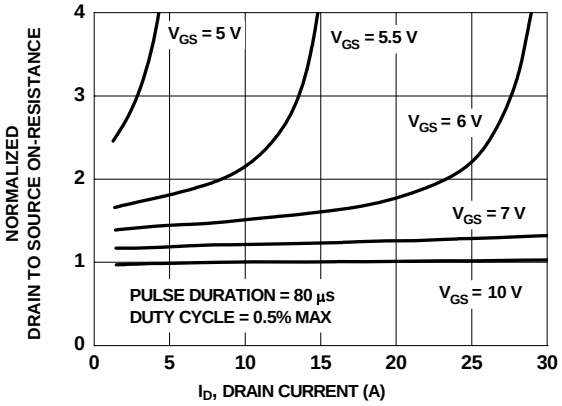


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

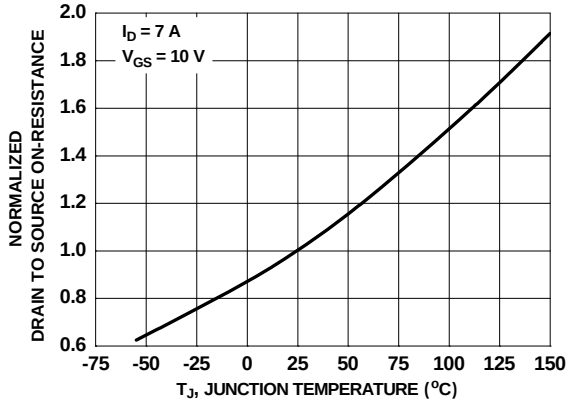


Figure 3. Normalized On-Resistance vs Junction Temperature

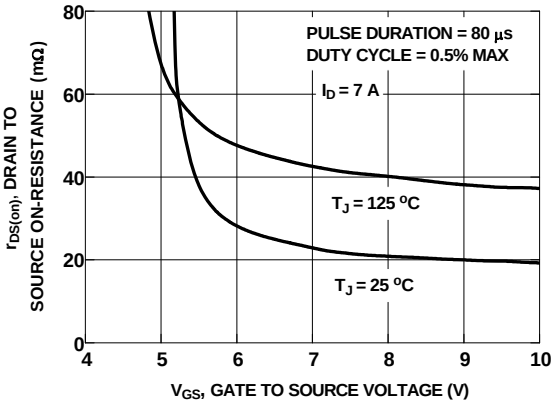


Figure 4. On-Resistance vs Gate to Source Voltage

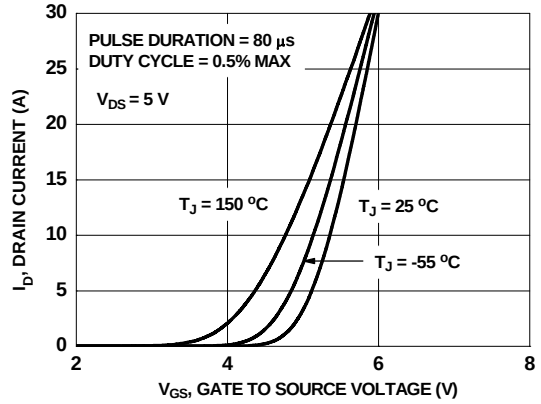


Figure 5. Transfer Characteristics

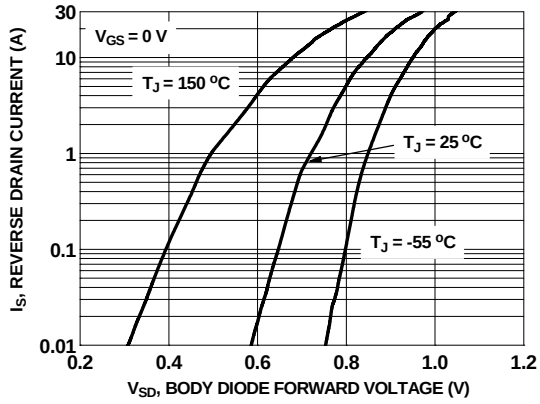


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

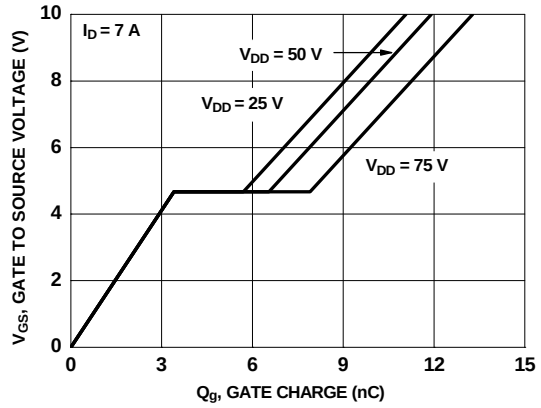


Figure 7. Gate Charge Characteristics

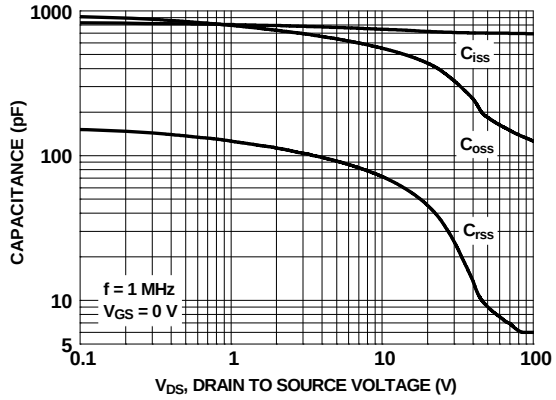


Figure 8. Capacitance vs Drain to Source Voltage

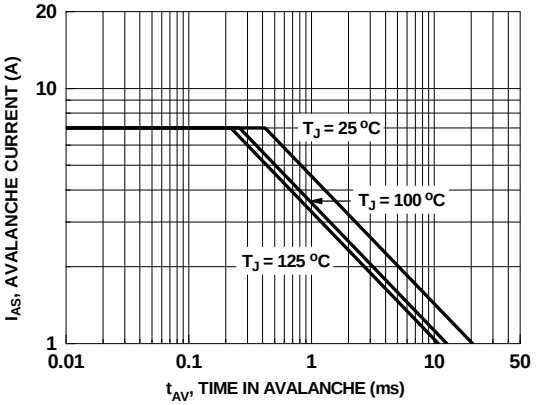


Figure 9. Unclamped Inductive Switching Capability

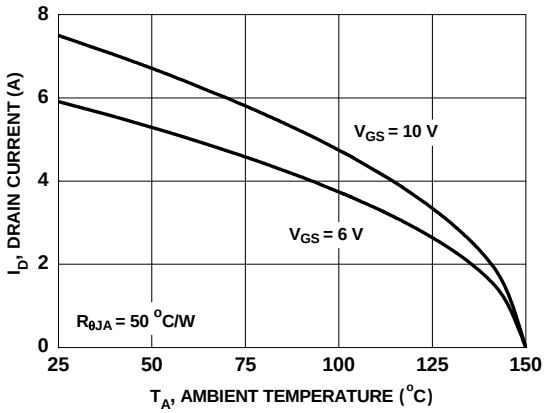


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

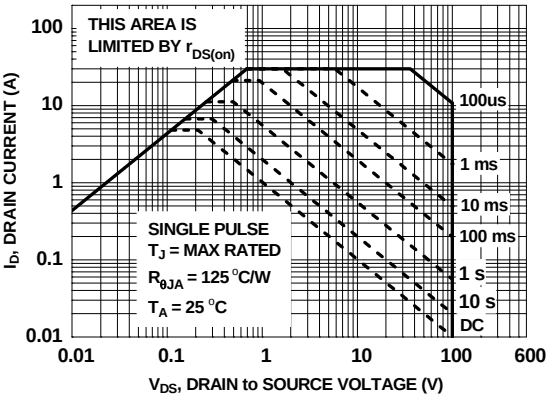


Figure 11. Forward Bias Safe Operating Area

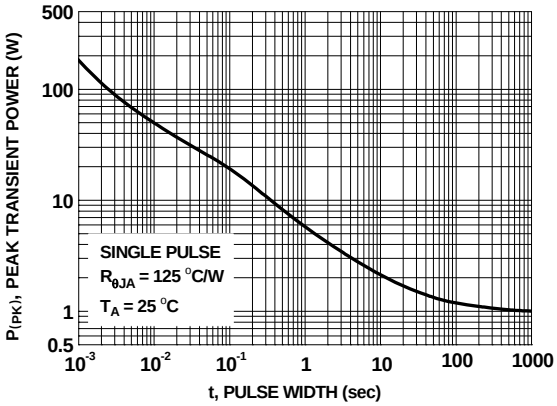


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

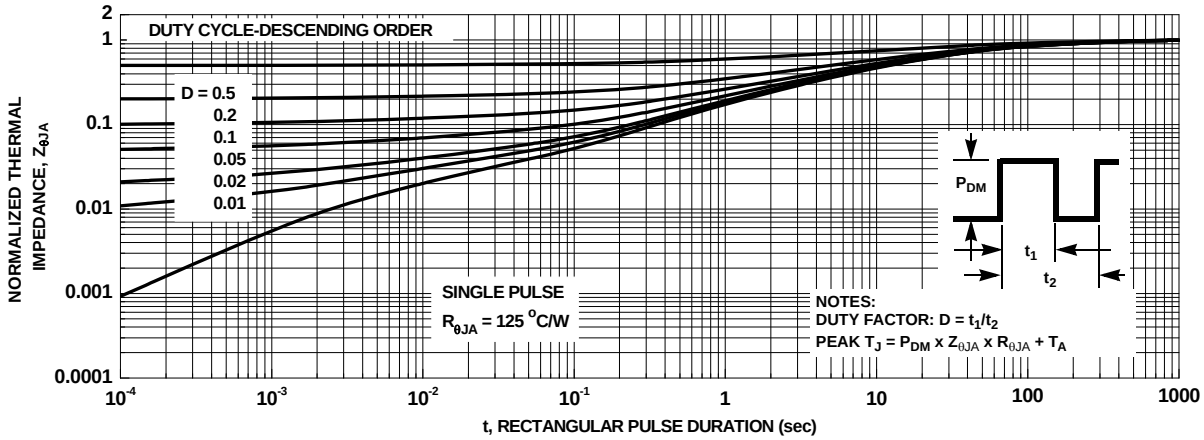
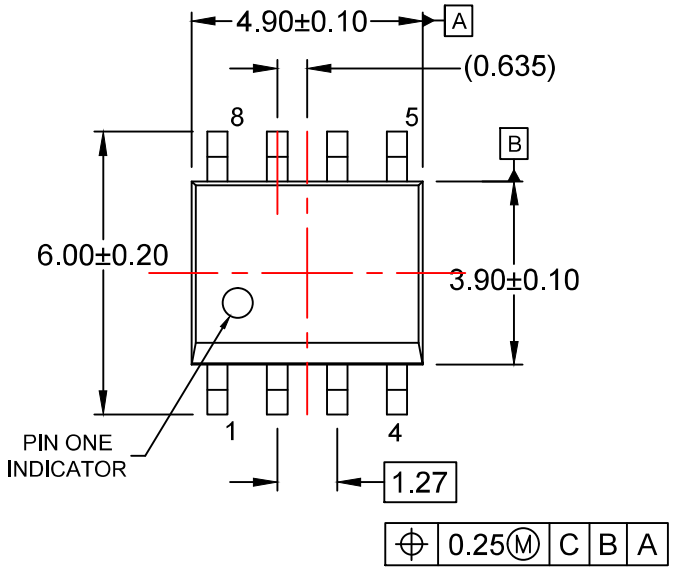
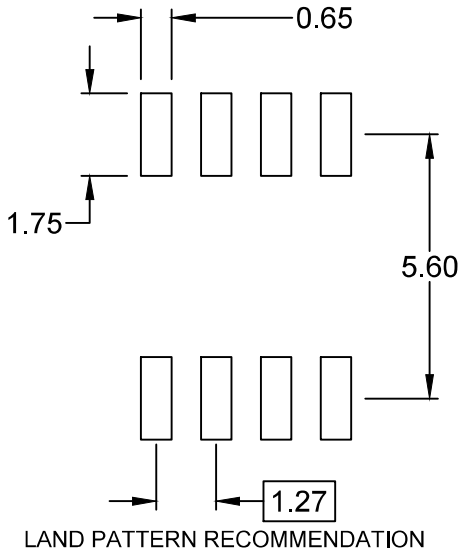
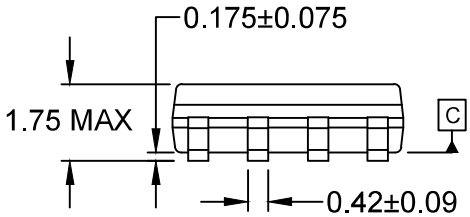


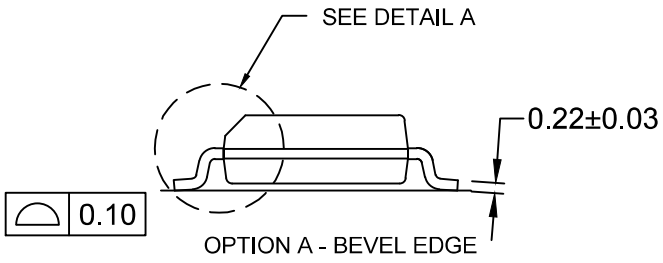
Figure 13. Junction-to-Ambient Transient Thermal Response Curve



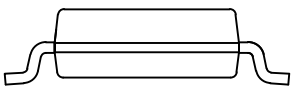


LAND PATTERN RECOMMENDATION

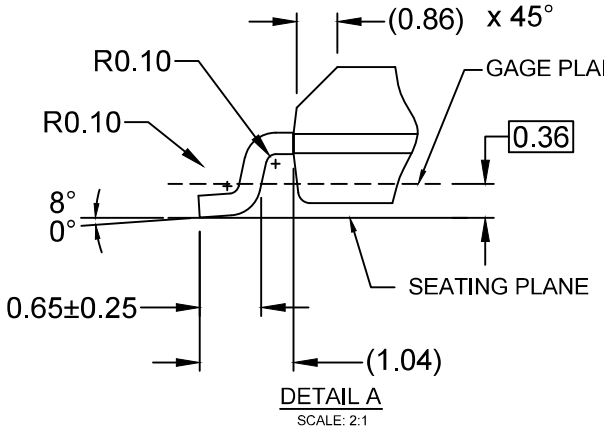




OPTION A - BEVEL EDGE



OPTION B - NO BEVEL EDGE



DETAIL A
SCALE: 2:1

NOTES:

A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
D) LANDPATTERN STANDARD: SOIC127P600X175-8M
E) DRAWING FILENAME: M08Arev16

FAIRCHILD.

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